

AMENDMENTS TO THE CLAIMS

Listing of the claims:

Following is a listing of all claims in the present application, which listing supersedes all previously presented claims:

1. (Currently Amended) A component ~~for a~~ in a film forming equipment for forming a thin film on a substrate, the component having a matrix material and ~~being~~ characterized ~~by that a metal~~ a first film layer electrochemically less noble than the matrix metal material ~~of said component~~ is formed on the surface of the matrix metal material ~~through thermal spraying, vapor depositing, sputtering, laminating or other process.~~

2. (Currently Amended) The component ~~as claimed in~~ of claim 1, characterized ~~by that~~ further having a second metal film layer electrochemically more noble than said matrix metal material ~~[[is]]~~ formed on the surface of said metal first film layer ~~through thermal spraying, vapor depositing, sputtering, laminating or other process.~~

3. (Withdrawn) A method of cleaning a component for a film forming equipment, characterized by that after a thin film has been formed on the substrate by the film forming equipment, the component as claimed in claim 1 or 2 is dipped in a cleaning fluid to remove an deposited film consisting of the film forming material from the component.

4. (Withdrawn) The method as claimed in claim 3, characterized by that a positive electric field is applied to the matrix metal material of said component dipped in the cleaning fluid.